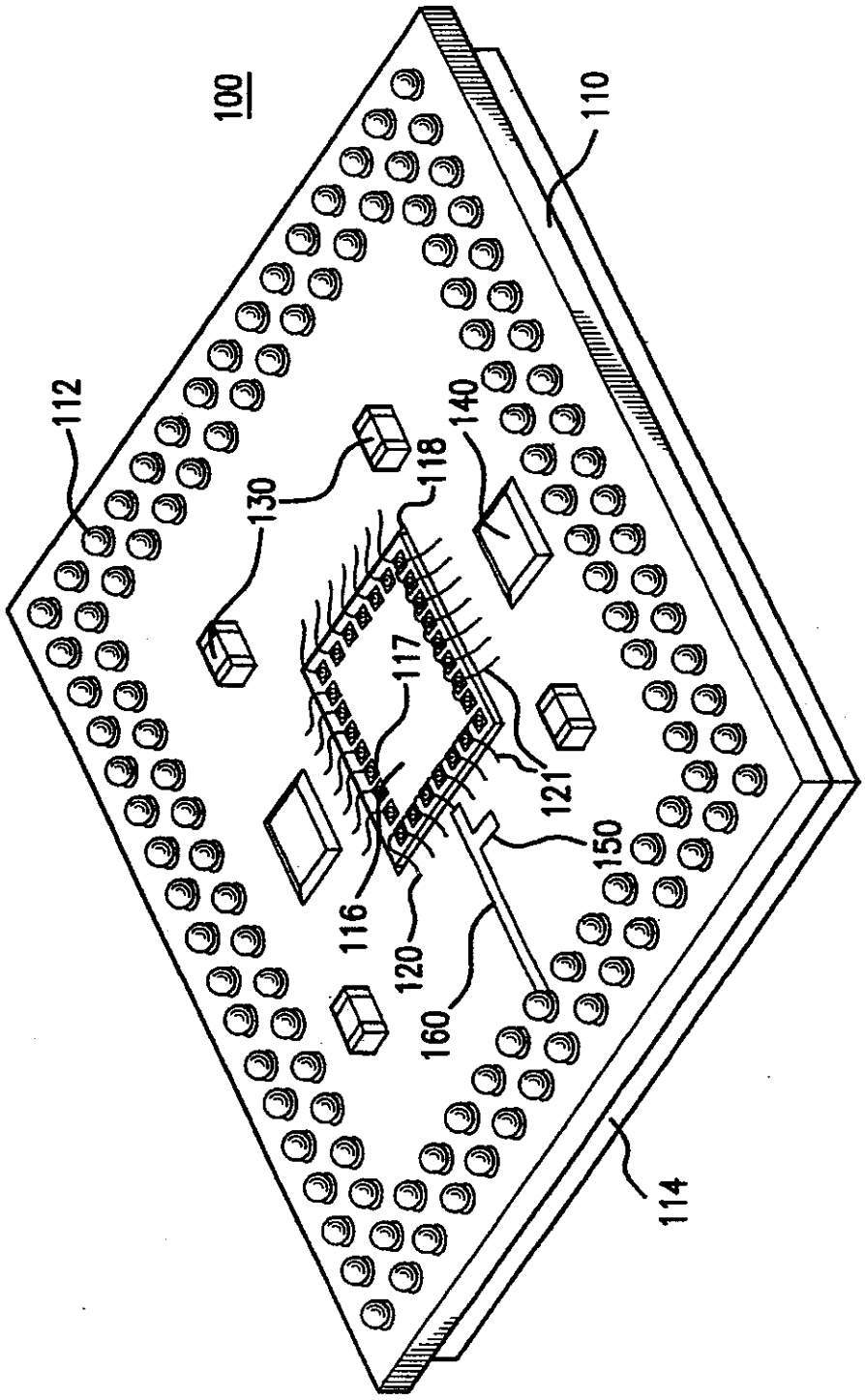



FIG. 1

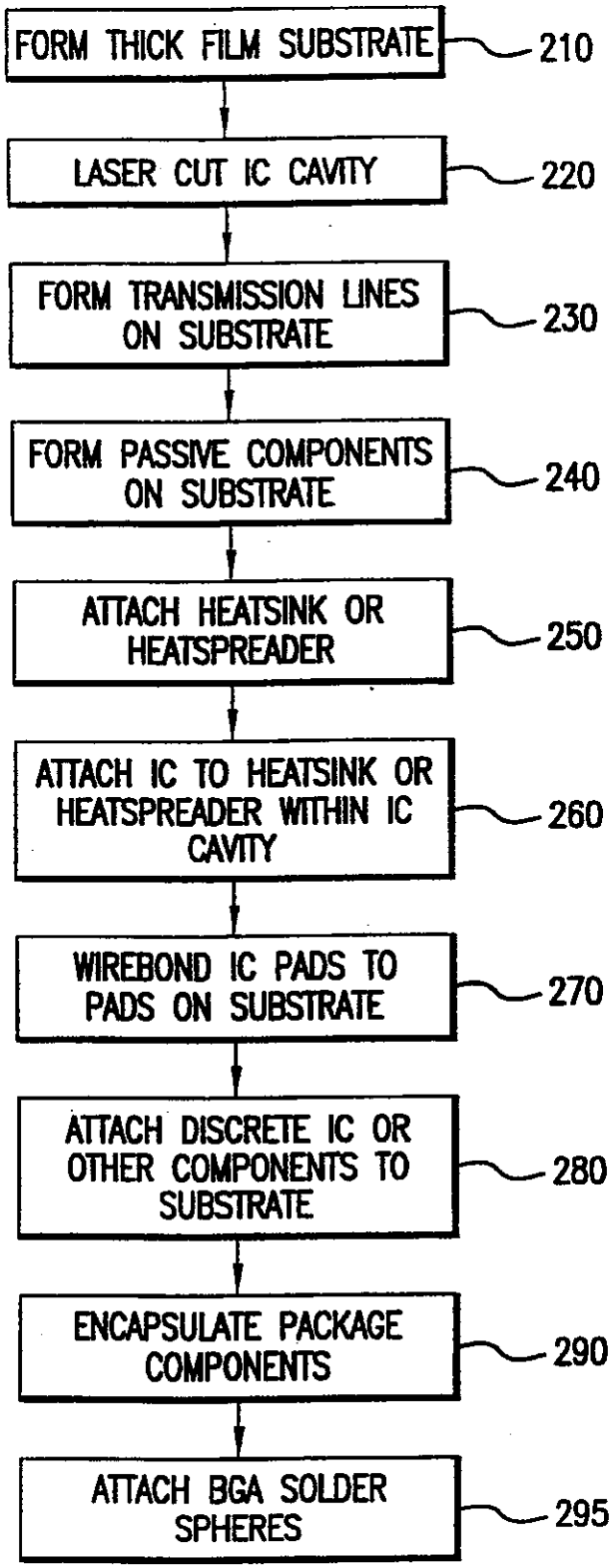

FORM THICK FILM SUBSTRATE
210
LASER CUT IC CAVITY
220
FORM TRANSMISSION LINES ON SUBSTRATE
230
FORM PASSIVE COMPONENTS ON SUBSTRATE
240
ATTACH HEATSINK OR HEATSPREADER
250
ATTACH IC TO HEATSINK OR HEATSPREADER WITHIN IC CAVITY
260
WIREBOND IC PADS TO PADS ON SUBSTRATE
270
ATTACH DISCRETE IC OR OTHER COMPONENTS TO SUBSTRATE
280
ENCAPSULATE PACKAGE COMPONENTS
290
ATTACH BGA SOLDER SPHERES
295

FIG.2